



[10191/3964]

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s) : Franz LAERMER et al.  
Serial No. : 10/530,612  
Filed : December 30, 2005  
For : **PLASMA SYSTEM AND METHOD FOR  
ANISOTROPICALLY ETCHING STRUCTURES  
INTO A SUBSTRATE**

Art Unit : 1792  
Examiner : Maki A. Angadi  
Confirmation No. : 6739

"Do Not Enter"  
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1/22/2010

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Date: January 5, 2010

Signature: \_\_\_\_\_

Richard M. Rosati (Reg. No. 31,792)

**AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. § 1.116**

SIR:

In response to a November 6, 2009 Final Office Action in the above-identified application, please amend, without prejudice, the above-captioned application as follows.

**Amendments to the Claims** are reflected in the **Listing of Claims**, which begins on page 2 of this paper.

**Remarks** begin on page 7 of this paper.